

Podsumowanie:

13 publikacji w czasopismach z listy filadelfijskiej

7 publikacji w innych czasopismach

2 książki

62 publikacje wygłoszonych na konferencjach międzynarodowych

2022

Jankowski M., Nazdrowicz, J., Zając, P.; Amrozik, P.; Szermer, M.; Maj, C.; Jabłoński, G., "Observation of Readout Temperature Dependence and Its Variability for the MEMS and ASIC System Specimens and Their PCB Testbenches," *2022 29th International Conference on Mixed Design of Integrated Circuits and System (MIXDES)*, 2022, pp. 110-115,

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Jankowski, M.; Zając, P.; Amrozik, P.; Szermer, M.; Maj, C.; Jabłoński, G.; Nazdrowicz, J. Thermal Performance of a Capacitive Comb-Drive MEMS Accelerometer: Measurements vs. Simulation. *Energies* **2021**, *14*, 7462

P. Zając, "Comparison of cooling performance of manifold and straight microchannel heat sinks using CFD simulation," 2021 22nd International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems (EuroSimE), 2021, pp. 1-4

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